ADVANCED SURFACE SCIENCE & INTERFACIAL PHYSICS PROTOCOL

Plasma and Corona Surface Treatments: Activating Silicone for High-Bond Printing and Tape Attachment

Document Ref: WP-2026-ST136-07 | Process Standards: ASTM D7490 Contact Angle Evaluation & ASTM D3359 Cross-Hatch Tape Trials | Reemane Surface Science Lab

1. Executive Summary: The Interfacial Inertness of Polysiloxanes

Silicone elastomers are widely utilized due to their exceptional thermal resistance, flexibility, and stability. However, cured silicone possesses a highly challenging physical property for post-molding secondary operations: an extremely low surface energy layer, typically hovering around $22 ext{ mN/m}$ (or $ ext{dynes/cm}$). This inert, hydrophobic state is caused by the dense orientation of non-polar methyl ($-CH_3$) groups along the backbone of the siloxane chain, creating an effective barrier that repels standard adhesives, printing inks, and bonding agents.

When engineering requirements mandate the application of double-sided acrylic tapes (such as high-bond 3M 300LSE adhesive systems) or precise multi-color screen printing graphics, raw silicone substrates trigger immediate adhesive failure or ink flaking. Overcoming this interfacial barrier requires surface modification. High-voltage **Plasma and Corona surface treatments** disrupt this chemical inertness, functionalizing the top molecular layers to achieve reliable bond strength without modifying core mechanical attributes.

> ***Interfacial Axiom: Mechanical bonding alone cannot sustain permanent adhesion on raw siloxane; high-voltage gas discharge is required to actively split the inert surface bonds and graft polar, hydrophilic functional groups.***

2. Kinetic Mechanisms: Corona Discharge vs. Atmospheric Plasma

Industrial surface modification relies on generating highly reactive gas states via localized electrical discharge. While both processes disrupt surface inertness, their application methods and gaseous physics differ:

- **Corona Discharge Treatment:** This process passes high-voltage AC current across a narrow electrode gap under atmospheric pressure. The electrical discharge ionizes the passing air, creating a localized corona cloud. As silicone components pass beneath this array, free electrons collide with the siloxane chain with sufficient energy to break carbon-hydrogen bonds. This mechanism converts non-polar surfaces into reactive zones, making it an exceptional approach for high-speed, continuous profiles like extruded tubes or flat sheets.
- **Atmospheric Plasma Treatment:** This setup forces pressurized gas—typically compressed air, pure oxygen ($ ext{O}_2$), or nitrogen ($ ext{N}_2$)—through a high-voltage plasma discharge nozzle. This process creates a dense stream of ionized gas, free radicals, and metastable atoms that are directed onto the silicone part surface. Plasma treatment delivers a higher concentration of active chemical species,

making it the ideal process for complex 3D molded shapes, deep enclosures, and precision electronic keypads.

3. Chemical Functionalization and Adhesion Engineering

The core transformation achieved by electric discharge treatments is the conversion of a hydrophobic surface into a hydrophilic interface. The high-energy plasma stream breaks down non-polar carbon-hydrogen bonds on the silicone surface, creating highly reactive free radical sites. These radicals immediately recombine with moisture and oxygen in the ambient air, grafting polar functional groups—predominantly hydroxyl ($-OH$), carbonyl ($=O$), and carboxyl ($-COOH$) groups—directly onto the surface lattice.

This molecular shift raises the surface energy of treated silicone from $22 ext{ mN/m}$ to a highly reactive range of $48 ext{ to }60 ext{ mN/m}$. Water droplet contact angles drop from a bead-forming 100° down to a wet-spreading angle beneath 30° (validated via **ASTM D7490**). This wetting behavior allows liquid inks and pressure-sensitive acrylic adhesives to flow uniformly across the modified micro-texture, establishing strong covalent bonds and interlocking molecular chains.

Surface Activation Dynamics and Adhesion Performance Profile

Surface Treatment State	Surface Energy	Water Contact Angle	3M 300LSE Peel Bond	Ink Adhesion Class
Raw Untreated Silicone	~ 22 mN/m	100° - 115°	< 1.5 N/cm (Delaminates)	0B (Total Flaking)
Corona Discharge (Air)	**42 - 48 mN/m**	**40° - 50°**	**6.5 N/cm (Substrate Tears)**	4B (Trace Edge Loss)
Atmospheric Plasma (O2 Blasted)	**52 - 60 mN/m**	**15° - 28°**	**> 9.0 N/cm (Substrate Tears)**	**5B (0% Ink Loss)**

4. The Hydrophobic Recovery Window: Managing Production Shelf-Life

A critical operational variable that sourcing and production managers must account for when planning surface treatments is **hydrophobic recovery**. The reactive state achieved by corona and plasma exposure is temporary. Because polymer chains retain high flexibility, the grafted polar functional groups slowly rotate inward toward the bulk elastomer matrix to minimize surface energy states, while untreated low-molecular-weight silicone fluid chains migrate outward to the surface.

This recovery mechanism means treated parts gradually revert to their initial hydrophobic, low-surface-energy state over time. Depending on compound formulations, storage temperatures, and handling conditions, the optimal activation window typically lasts from 2 to 24 hours. To ensure maximum bond integrity, Reemane coordinates strict production scheduling, executing screen printing or 3M tape application steps immediately following the surface activation sequence.

5. DFM Frameworks for Advanced Surface Activation Integration

Integrating high-voltage surface treatments into mass production requires strict adherence to custom tool design and processing rules. First, parts must be completely free of residual external mold oils or greasy release chemistry. If a factory sprays cheap petroleum release agents to eject parts, these oils block the plasma arc from contacting the true siloxane base. Molds must utilize premium **S136 tool steel with SPI-A1 diamond mirror polishing** to facilitate clean, chemical-free release.

Second, 2D component drawings must explicitly define targeted activation zones. If an automotive enclosure strip requires high-bond tape integration along its flat base but must keep its external aesthetic lips free from plasma arc discoloration or micro-texture changes, custom shielding fixtures must be designed into the automated plasma line. Laying out these parameters early in the CAD review ensures repeatable, localized surface activation control during production scaling.

Optimize Your High-Bond Surface Manufacturing Integrity

Eliminate ink flaking defects, secure high-bond 3M adhesive tape attachment, and leverage automated surface activation lines to achieve permanent component integration. To evaluate custom plasma shielding layouts, schedule ASTM contact angle validation trials, or coordinate process audits, contact our engineering division directly at sales@siliconefactories.com or explore our global technical network at www.siliconefactories.com.